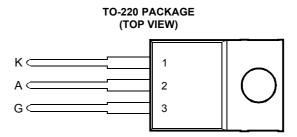
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- 5 A Continuous On-State Current
- 30 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 200 μA



Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING			VALUE	UNIT
	TIC106D		400	
Panetitive neak off state voltage (see Nate 1)	TIC106M	V	600	V
Repetitive peak off-state voltage (see Note 1)	TIC106S	V _{DRM}	700	
	TIC106N		800	
	TIC106D		400	
Depetitive peak reverse veltage	TIC106M	N	600	V
Repetitive peak reverse voltage	TIC106S	V _{RRM}	700	
	TIC106N		800	
Continuous on-state current at (or below) 80°C case temperature (see Note 2)			5	A
Average on-state current (180° conduction angle) at (or below) 80°C case temperature		IT(RMS)	3.2	A
(see Note 3)		I _{T(AV)}	3.2	
Surge on-state current at (or below) 25°C (see Note 4)		I _{TSM}	30	A
Peak positive gate current (pulse width \leq 300 μ s)		I _{GM}	0.2	A
Peak gate power dissipation (pulse width \leq 300 μ s)		P _{GM}	1.3	W
Average gate power dissipation (see Note 5)		P _{G(AV)}	0.3	W
Operating case temperature range		Τ _C	-40 to +110	°C
Storage temperature range			-40 to +125	°C
Lead temperature 1.6 mm from case for 10 seconds			230	°C

NOTES: 1. These values apply when the gate-cathode resistance R_{GK} = 1 k\Omega.

3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.

4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.

5. This value applies for a maximum averaging time of 20 ms.

PRODUCT INFORMATION

Information is current as of publication date. Products conform to specifications in accordance with the terms of Power Innovations standard warranty. Production processing does not necessarily include testing of all parameters.



^{2.} These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.

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electrical characteristics at 25°C case temperature (unless otherwise noted)

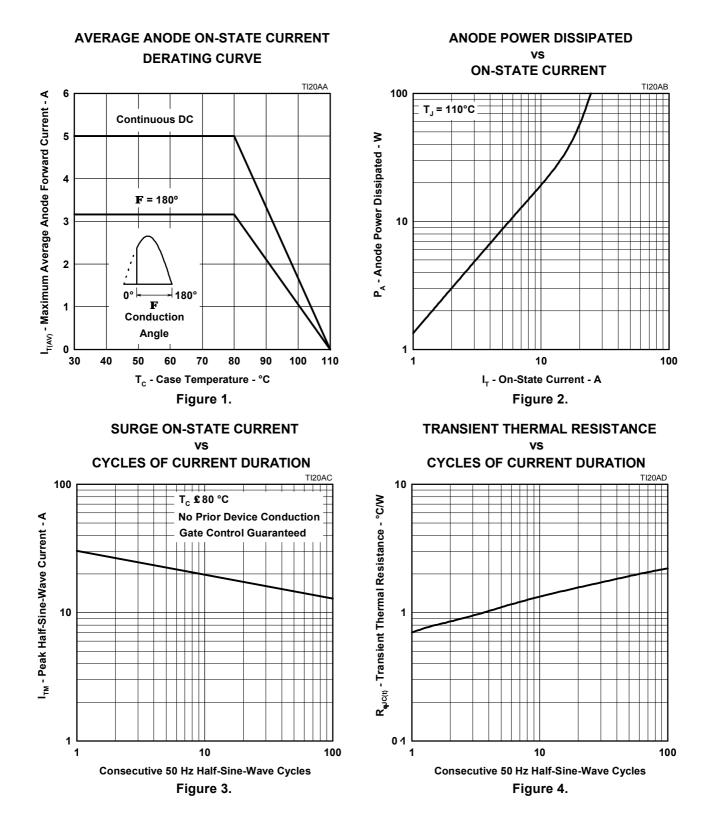
	PARAMETER		TEST CONDITIO	NS	MIN	TYP	MAX	UNIT
I _{DRM}	Repetitive peak off-state current	$V_{D} = rated V_{DRM}$	$R_{GK} = 1 \ k\Omega$	$T_{\rm C} = 110^{\circ}{\rm C}$			400	μA
I _{RRM}	Repetitive peak reverse current	V_{R} = rated V_{RRM}	I _G = 0	$T_{\rm C} = 110^{\circ}{\rm C}$			1	mA
I _{GT}	Gate trigger current	V _{AA} = 12 V	R _L = 100 Ω	t _{p(g)} ≥ 20 μs		5	200	μA
V _{GT}	Gate trigger voltage	V _{AA} = 12 V t _{p(g)} ≥ 20 µs	R _L = 100 Ω R _{GK} = 1 kΩ	$T_{C} = -40^{\circ}C$			1.2	
		V _{AA} = 12 V t _{p(g)} ≥ 20 µs	R _L = 100 Ω R _{GK} = 1 kΩ		0.4	0.6	1	V
		V _{AA} = 12 V t _{p(g)} ≥ 20 µs	R _L = 100 Ω R _{GK} = 1 kΩ	T _C = 110°C	0.2			
I _Н	Holding current	$V_{AA} = 12 V$ Initiating I _T = 10 mA	$R_{GK} = 1 \ k\Omega$	$T_C = -40^{\circ}C$			8	mA
		$V_{AA} = 12 V$ Initiating I _T = 10 mA	$R_{GK} = 1 \ k\Omega$				5	
V _T	Peak on-state voltage	I _T = 5 A	(See Note 6)				1.7	V
dv/dt	Critical rate of rise of off-state voltage	V_D = rated V_D	$R_{GK} = 1 \ k\Omega$	$T_{C} = 110^{\circ}C$		10		V/µs

NOTE 6: This parameter must be measured using pulse techniques, $t_p = 300 \ \mu s$, duty cycle $\le 2 \ \%$. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

PARAMETER		MIN	ТҮР	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			3.5	°C/W
R _{0JA}	Junction to free air thermal resistance			62.5	°C/W

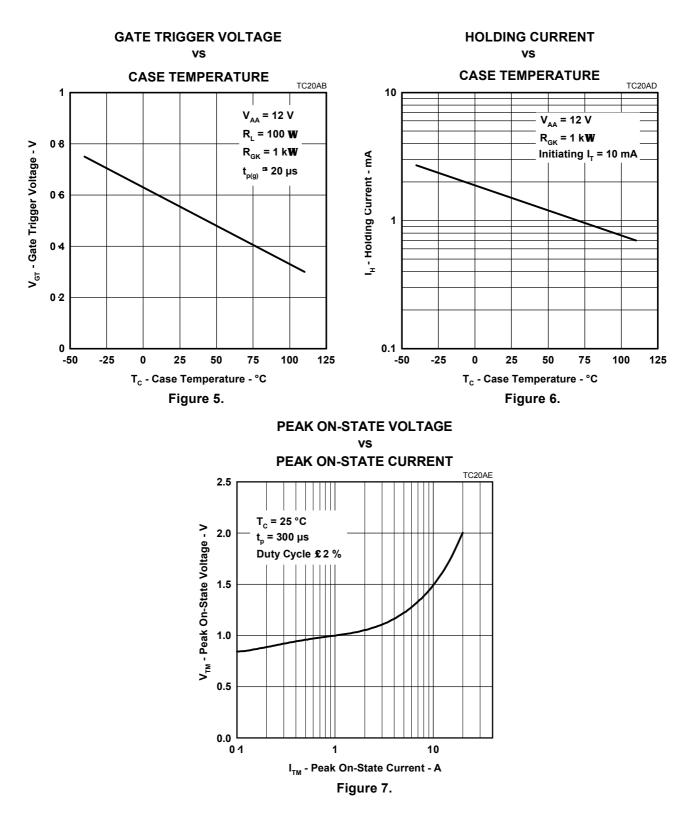
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THERMAL INFORMATION



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TYPICAL CHARACTERISTICS

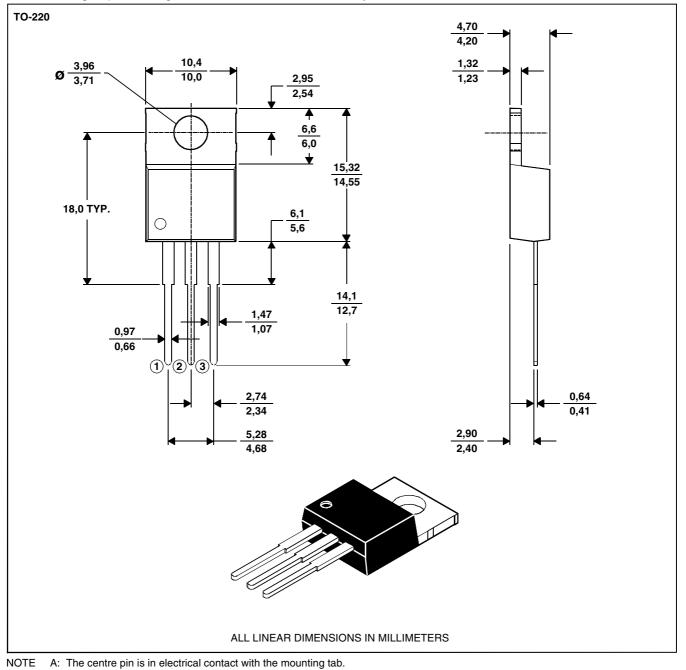
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.





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